

Refining & Chemicals Polymers Technical Data Sheet Specialty Compounds Polypropylene Rotational Moulding Produced in Europe

Description

TPSeal[®] PP 10T1 is a metallocene random copolymer Polypropylene (mPP) Compound. TPSeal[®] PP 10T1 is intended for the manufacture of rotomoulded items and available in natural, in pellets or in powder.

Main Characteristics

Its specific molecular structure ensures:

- ✓ Low warpage, low shrinkage
- ✓ High gloss
- ✓ Good transparency as monolayer
- Excellent contact transparency in multi-layer applications

Application

Structural parts, design (furniture), house appliances such as lamp, ...

Properties

Property	Method	Unit	Typical value (*)
Melt Flow Rate (230°C-2.16kg)	ISO 1133/D	g/10min	10.0
Melting Temperature	ISO 11357	°C	140
Vicat Softening Point (Method A50)	ISO 306	°C	124
Heat Deflection Temperature (Method B)	ISO 75	°C	92
Tensile modulus	ISO 527	MPa	1400
Tensile strength @yield	ISO 527	MPa	33

(*) Data not intended for specification purposes

Processing conditions

It is recommended to keep product dry prior use for production.

Handling and storage

Please refer to the material safety data sheet (MSDS) for handling and storage information. It is advisable to convert the product within one year after delivery provided storage conditions are used as given in the MSDS of our product.

MSDS may be obtained from the website: <u>http://www.polymers.total.com/</u>

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